

Description

The SQ4946CEY-T1_GE3 uses advanced trench technology to provide excellent R_{DS(ON)}, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

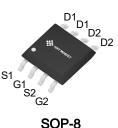
$$\begin{split} V_{DS} &= 60V \ I_{D} = 6.5 \, A \\ R_{DS(ON)} &< 36 m\Omega \ @ \, V_{GS} = 10 \, V \\ R_{DS(ON)} &< 48 m\Omega \ @ \, V_{GS} = 4.5 V \end{split}$$

Application

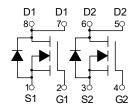
Battery protection

Load switch

Uninterruptible power supply



SOP-8 (SO-8)



Dual N-Channel MOSFET

Package Marking and Ordering Information

Product ID	Pack	Brand	Qty(PCS)
SQ4946CEY-T1_GE3	SOP-8(SO-8)	HXY MOSFET	3000

Absolute Maximum Ratings@Tj=25 °C(unless otherwise specified)

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	60	V
V _G s	Gate-Source Voltage	<u>+</u> 20	V
I _D @T _A =25°C	Drain Current, V _{GS} @ 4.5V ³	6.5	Α
I _D @T _A =70°C	Drain Current, V _{GS} @ 4.5V ³	5	Α
Ірм	Pulsed Drain Current ¹	30	Α
P _D @T _A =25°C	Total Power Dissipation	2.1	W
Тѕтс	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C
Rthj-a	Maximum Thermal Resistance, Junction- ambient ³	60	°C/W

SQ4946CEY-T1_GE3

Dual N-Channel Enhancement Mode MOSFET

Electrical Characteristics (T_A=25°C unless otherwise noted)

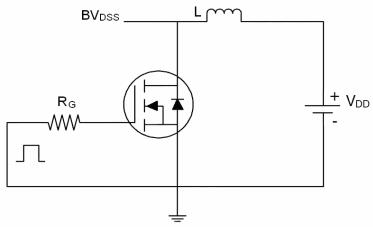
Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics				•	•	
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA 60		69	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =60V,V _{GS} =0V	V _{DS} =60V,V _{GS} =0V -		1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)				•	•	
Gate Threshold Voltage	$V_{GS(th)}$	V _{DS} =V _{GS} ,I _D =250µA	1.0	1.4	2.0	V
	R _{DS(ON)}	V _{GS} =10V, I _D =6A		32	36	mΩ
Drain-Source On-State Resistance		V _{GS} =4.5V, I _D =4A		34	48	mΩ
Forward Transconductance	G FS	V_{DS} =5 V , I_{D} =6 A		20	-	S
Dynamic Characteristics (Note4)	<u></u>		<u> </u>	ı	l l	
Input Capacitance	C _{lss}	V 051/1/ 01/		1920		PF
Output Capacitance	Coss	$V_{DS}=25V,V_{GS}=0V,$		155		PF
Reverse Transfer Capacitance	C _{rss}	F=1.0MHz		116		PF
Switching Characteristics (Note 4)	<u> </u>		•	I.	I.	
Turn-on Delay Time	t _{d(on)}		-	8	-	nS
Turn-on Rise Time	t _r	V_{DS} =30V, R_L =4.7 Ω	-	5	-	nS
Turn-Off Delay Time	t _{d(off)}	V_{GS} =10 V , R_{GEN} =3 Ω	-	29	-	nS
Turn-Off Fall Time	t _f		-	6	-	nS
Total Gate Charge	Q_g	V 20VI CA	-	50	-	nC
Gate-Source Charge	Q_{gs}	V_{DS} =30V, I_{D} =6A, V_{GS} =10V	-	8	-	nC
Gate-Drain Charge	Q_{gd}	V _{GS} -10V	-	16	-	nC
Drain-Source Diode Characteristic	cs			•	•	
Diode Forward Voltage (Note 3)	V_{SD}	V _{GS} =0V,I _S =6A	-	-	1.2	V
Diode Forward Current (Note 2)	Is		-	-	7	Α
Reverse Recovery Time	t _{rr}	TJ = 25°C, I _F =7A	-	35	-	nS
Reverse Recovery Charge	Qrr	$di/dt = 100A/\mu s^{(Note3)}$	-	43	-	nC
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

Notes:

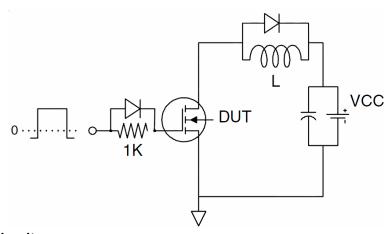
- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production

Test Circuit

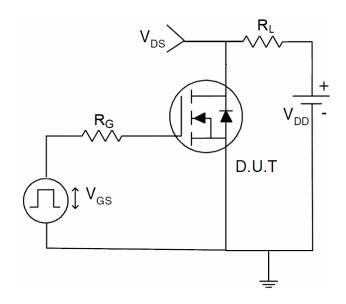
1) E_{AS} test Circuits



2) Gate charge test Circuit

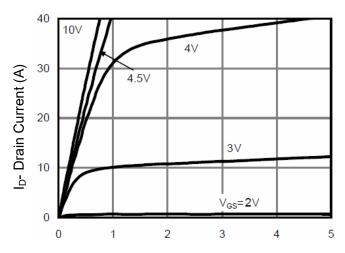


3) Switch Time Test Circuit

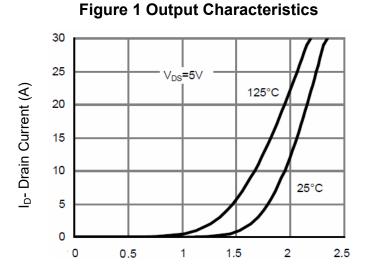




Typical Electrical and Thermal Characteristics (Curves)



Vds Drain-Source Voltage (V)



Vgs Gate-Source Voltage (V)
Figure 2 Transfer Characteristics

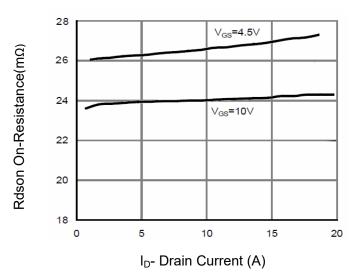


Figure 3 Rdson- Drain Current

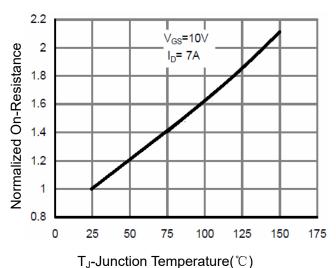


Figure 4 Rdson-JunctionTemperature

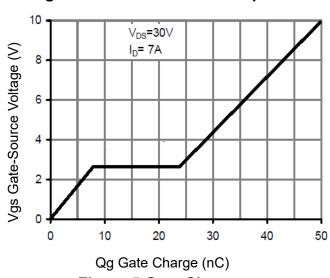


Figure 5 Gate Charge

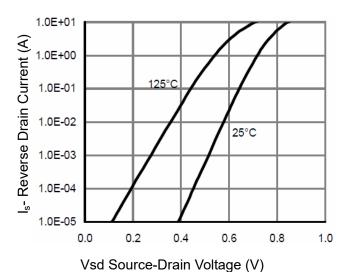


Figure 6 Source- Drain Diode Forward



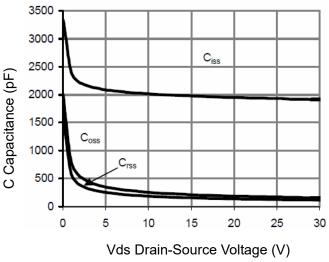


Figure 7 Capacitance vs Vds

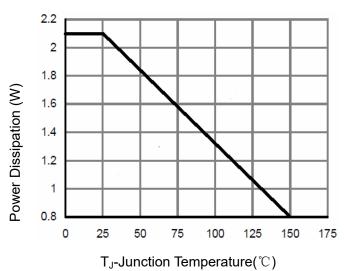


Figure 9 Power De-rating

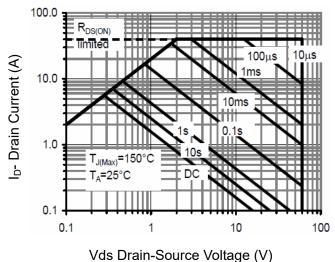


Figure 8 Safe Operation Area

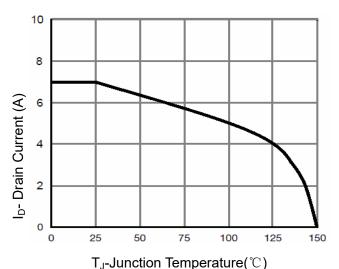


Figure 10 Current De-rating

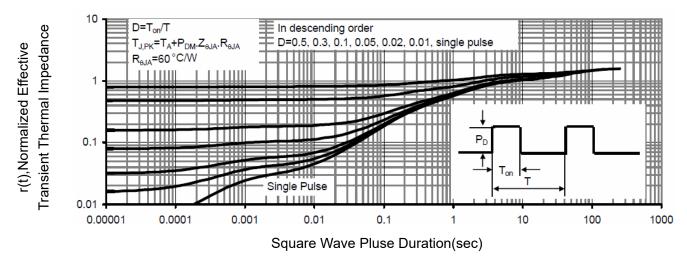
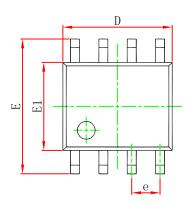
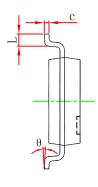
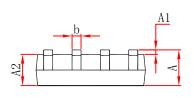


Figure 11 Normalized Maximum Transient Thermal Impedance

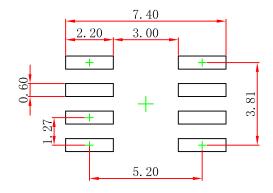
SOP-8(SO-8) Package Outline Dimensions







Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min	Max	Min	Max	
A	1.350	1.750	0.053	0.069	
A1	0.100	0. 250	0.004	0.010	
A2	1.350	1.550	0.053	0.061	
b	0.330	0.510	0.013	0.020	
c	0.170	0. 250	0.007	0.010	
D	4.800	5. 000	0. 189	0. 197	
e	1.270 (BSC)		0.050 (BSC)		
E	5.800	6. 200	0. 228	0. 244	
E1	3.800	4. 000	0. 150	0. 157	
L	0.400	1. 270	0.016	0.050	
θ	0°	8°	0°	8°	



- Note: 1.Controlling dimension:in millimeters.
- 2.General tolerance:± 0.05mm.
 3.The pad layout is for reference purposes only.



Attention

- Any and all HUA XUAN YANG ELECTRONICS products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your HUA XUAN YANG ELECTRONICS representative nearest you before using any HUA XUAN YANG ELECTRONICS products described or contained herein in such applications.
- HUA XUAN YANG ELECTRONICS assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all HUA XUAN YANG ELECTRONICS products described or contained herein.
- Specifications of any and all HUA XUAN YANG ELECTRONICS products described or contained herein stipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.
- HUA XUAN YANG ELECTRONICS CO.,LTD. strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could give rise to accidents or events that could endanger human lives, that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.
- In the event that any or all HUA XUAN YANG ELECTRONICS products(including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law.
- No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of HUA XUAN YANG ELECTRONICS CO.,LTD.
- Information (including circuit diagrams and circuit parameters) herein is for example only; it is not guaranteed for volume production.

 HUA XUAN YANG ELECTRONICS believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringements of intellectual property rights or other rights of third parties.